IPC ASSOCIATION COI ELECTRONICS INI	© Copyright 2005.	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under international and Pan-American copyright conventions.		der both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				ials and Mfc Information				
upplier In	nformation								,					
Company name*			Company unique ID			J	Unique ID Authority				Response Date*			
nsemi										2024-05-03				
Contact Name			Title - Contact			I	Phone - Contact*				Email - Contact*			
Product-Env-	-Stewards	Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com				
uthorized R	epresentative*	Title - Representative			I	Phone - Representative*				Email - Representative*				
Product-Env-Stewards			Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com			
Re	equester Item Number	Mfr Item	•	ber Mfr Item Name			Effective Date	Version	M	Ianufacturing Site	W	eight*	UOM	Unit Type
		FDMT80080DC FET 80V 1.35 mOh		nms PQFN88		2024-05-03		PBB		25	9.55383	mg	Each	
	ring Process Informa				000 May	D. d		D 1 T		M. Ti . D. I	T	N. 1		
2 ,			•		STD-020 MSL	Rating	Peak Process Body Temperate		•				er of Reflow Cyc	cles
•	ntte Tin (Sn) - annealed	[0	CU Alloy	1			260		C	30	seconds	3		
omments														
	mum time at peak tempera	8												
r more info	ormation regarding materia	d composition	please refer t	o page 3										

RoHS Material Composition Declaration			Declaration Type *	Detailed						
ricetive 2015/863/EU amending RoHS irrective 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its paragraph. If the Company and the Supplier supplier has provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Standard Terms and Conditions of Sale applicable to such										
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.										
Supplier Digital Signature Ra	astislav Drska	-En								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	75.064	mg	Supplier	Silver (Ag)	7440-22-4		3.754	mg
			Supplier	Zinc (Zn)	7440-66-6		0.09	mg
			Supplier	Iron (Fe)	7439-89-6		1.802	mg
			Supplier	Copper (Cu)	7440-50-8		69.358	mg
			Supplier	Phosphorus (P)	7723-14-0		0.06	mg
Die	6.33566	mg	Supplier	Silicon (Si)	7440-21-3		6.3357	mg
Die Attach Solder	14.0725	mg	Supplier	Silver (Ag)	7440-22-4		0.3518	mg
			A	Lead (Pb)	7439-92-1	7a	13.0171	mg
			Supplier	Tin (Sn)	7440-31-5		0.7036	mg
Lead Frame	81.5831	mg	Supplier	Silver (Ag)	7440-22-4		4.0796	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0979	mg
			Supplier	Iron (Fe)	7439-89-6		1.9582	mg
			Supplier	Copper (Cu)	7440-50-8		75.3821	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0653	mg
Mold Compound-Black	65.6505	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		4.2801	mg
			Supplier	Carbon Black (C)	1333-86-4		0.1317	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		57.9463	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		3.2924	mg
Plating	8.43273	mg	Supplier	Tin (Sn)	7440-31-5		8.4327	mg
Wire Bond - Cu	8.41535	mg	Supplier	Palladium (Pd)	7440-05-3		0.1515	mg
			Supplier	Copper (Cu)	7440-50-8		8.2639	mg